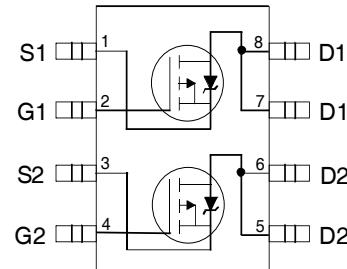


## Features

- Trench Technology
- Ultra Low On-Resistance
- Dual P-Channel MOSFET
- Available in Tape & Reel
- Lead-Free



<b>V<sub>DSS</sub></b>	<b>R<sub>D(on)</sub> max</b>	<b>I<sub>D</sub></b>
<b>-30V</b>	21mΩ@V <sub>GS</sub> = -10V	-8.0A
	32mΩ@V <sub>GS</sub> = -4.5V	-6.8A

Top View

## Absolute Maximum Ratings

	Parameter	Max.	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
I <sub>D</sub> @ T <sub>A</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V	-8.0	A
I <sub>D</sub> @ T <sub>A</sub> = 70°C	Continuous Drain Current, V <sub>GS</sub> @ -10V	-6.4	
I <sub>DM</sub>	Pulsed Drain Current①	-32	
P <sub>D</sub> @ T <sub>A</sub> = 25°C	Maximum Power Dissipation③	2.0	W
P <sub>D</sub> @ T <sub>A</sub> = 70°C	Maximum Power Dissipation③	1.3	W
	Linear Derating Factor	16	mW/°C
V <sub>GS</sub>	Gate-to-Source Voltage	± 20	V
T <sub>J</sub> , T <sub>STG</sub>	Junction and Storage Temperature Range	-55 to + 150	°C

## Thermal Resistance

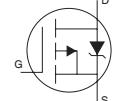
	Parameter	Max.	Units
R <sub>θJA</sub>	Maximum Junction-to-Ambient ③	62.5	°C/W

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	-30	—	—	V	$V_{\text{GS}} = 0\text{V}$ , $I_D = -250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}/\Delta T_J}$	Breakdown Voltage Temp. Coefficient	—	-0.018	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $I_D = -1\text{mA}$
$R_{\text{DS}(\text{on})}$	Static Drain-to-Source On-Resistance	—	17	21	m $\Omega$	$V_{\text{GS}} = -10\text{V}$ , $I_D = -8.0\text{A}$ ②
		—	26.8	32		$V_{\text{GS}} = -4.5\text{V}$ , $I_D = -6.8\text{A}$ ②
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	-1.0	—	-2.5	V	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = -250\mu\text{A}$
$g_{\text{fs}}$	Forward Transconductance	12	—	—	S	$V_{\text{DS}} = -10\text{V}$ , $I_D = -8.0\text{A}$
$I_{\text{DSS}}$	Drain-to-Source Leakage Current	—	—	-15	$\mu\text{A}$	$V_{\text{DS}} = -24\text{V}$ , $V_{\text{GS}} = 0\text{V}$
		—	—	-25		$V_{\text{DS}} = -24\text{V}$ , $V_{\text{GS}} = 0\text{V}$ , $T_J = 70^\circ\text{C}$
$I_{\text{GSS}}$	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{\text{GS}} = -20\text{V}$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{\text{GS}} = 20\text{V}$
$Q_g$	Total Gate Charge	—	52	78	nC	$I_D = -8.0\text{A}$
$Q_{\text{gs}}$	Gate-to-Source Charge	—	9.8	—		$V_{\text{DS}} = -15\text{V}$
$Q_{\text{gd}}$	Gate-to-Drain ("Miller") Charge	—	8.3	—		$V_{\text{GS}} = -10\text{V}$
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	—	13	20	ns	$V_{\text{DD}} = -15\text{V}$ , $V_{\text{GS}} = -10.0\text{V}$
$t_r$	Rise Time	—	15	23		$I_D = -1.0\text{A}$
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time	—	198	297		$R_G = 6.0\Omega$
$t_f$	Fall Time	—	98	147		$R_D = 15\Omega$ ②
$C_{\text{iss}}$	Input Capacitance	—	2675	—	pF	$V_{\text{GS}} = 0\text{V}$
$C_{\text{oss}}$	Output Capacitance	—	409	—		$V_{\text{DS}} = -25\text{V}$
$C_{\text{rss}}$	Reverse Transfer Capacitance	—	262	—		$f = 1.0\text{MHz}$

**Source-Drain Ratings and Characteristics**

	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	-2.0	A	MOSFET symbol showing the integral reverse p-n junction diode.
$I_{\text{SM}}$	Pulsed Source Current (Body Diode) ①	—	—	-32		
$V_{\text{SD}}$	Diode Forward Voltage	—	—	-1.2		$T_J = 25^\circ\text{C}$ , $I_S = -2.0\text{A}$ , $V_{\text{GS}} = 0\text{V}$ ②
$t_{\text{rr}}$	Reverse Recovery Time	—	37	56	ns	$T_J = 25^\circ\text{C}$ , $I_F = -2.0\text{A}$
$Q_{\text{rr}}$	Reverse Recovery Charge	—	36	54	nC	$dI/dt = -100\text{A}/\mu\text{s}$ ②

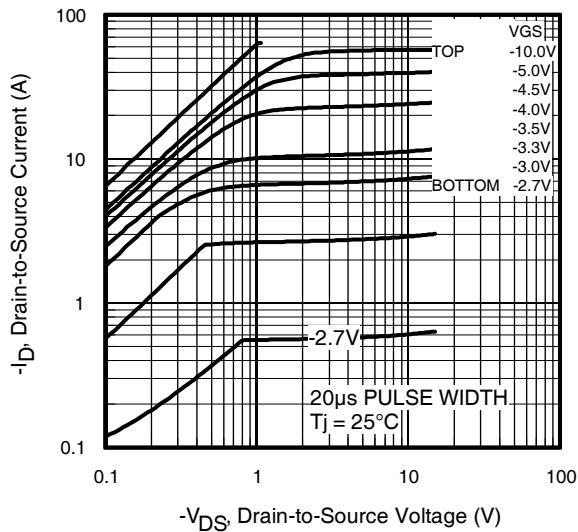


**Notes:**

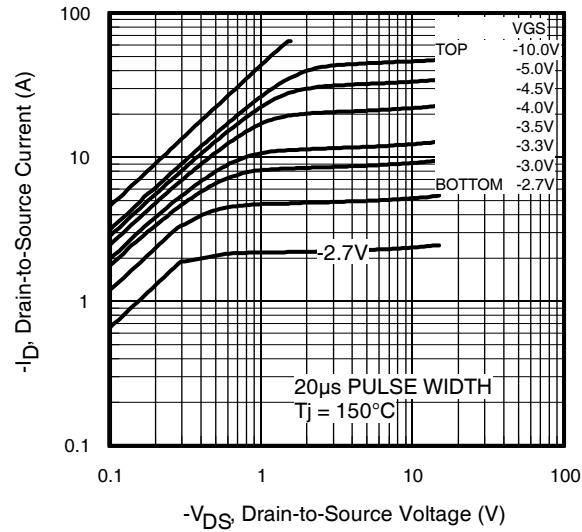
① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width  $\leq 400\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

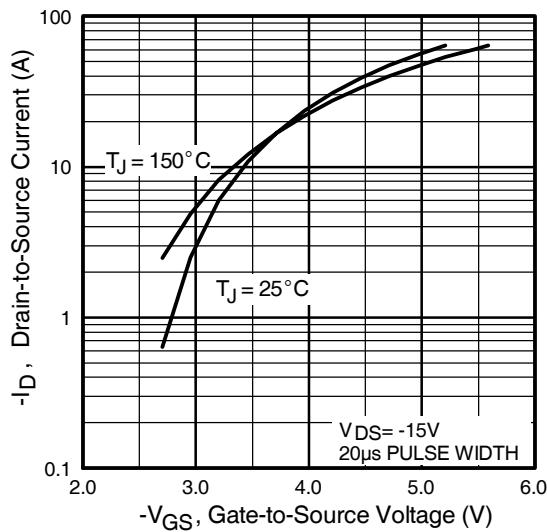
③ Surface mounted on FR-4 board,  $t \leq 10\text{sec}$ .



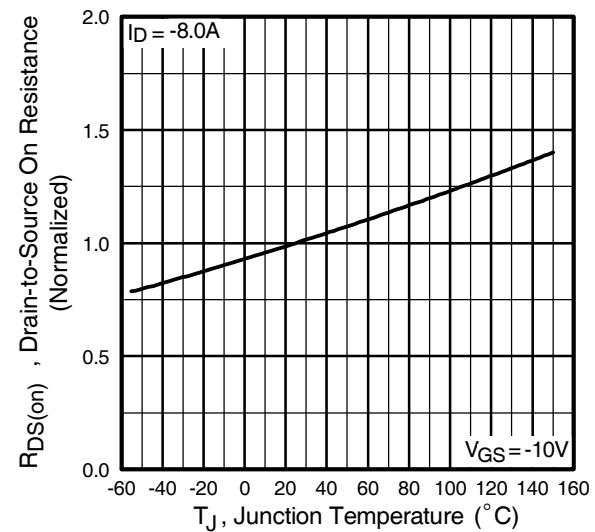
**Fig 1.** Typical Output Characteristics



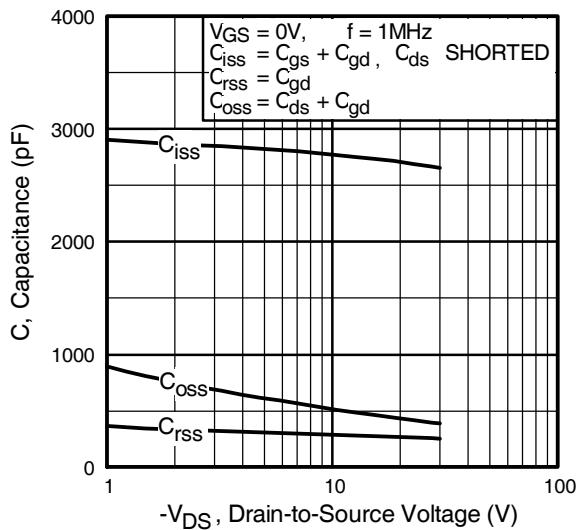
**Fig 2.** Typical Output Characteristics



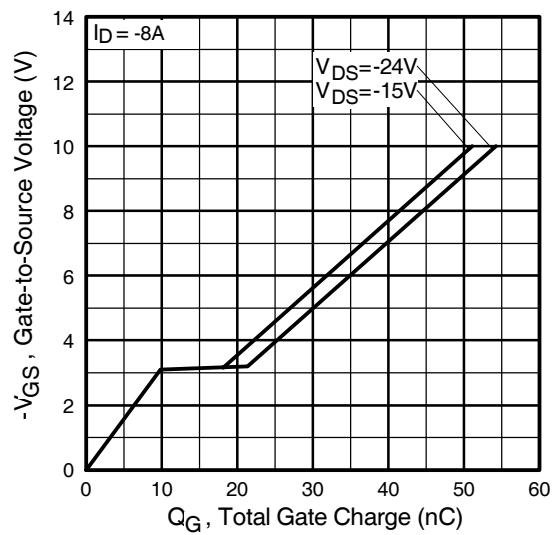
**Fig 3.** Typical Transfer Characteristics



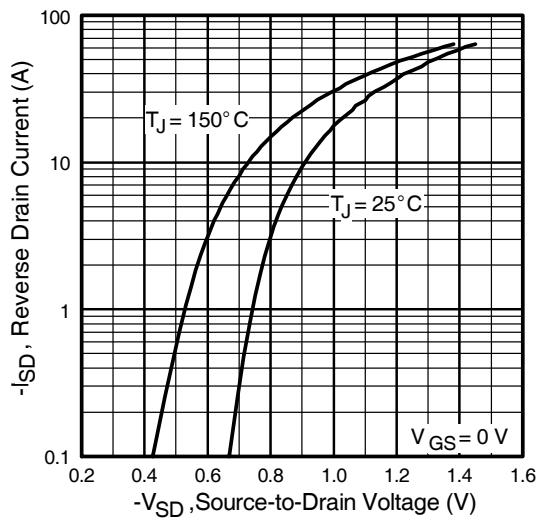
**Fig 4.** Normalized On-Resistance  
Vs. Temperature



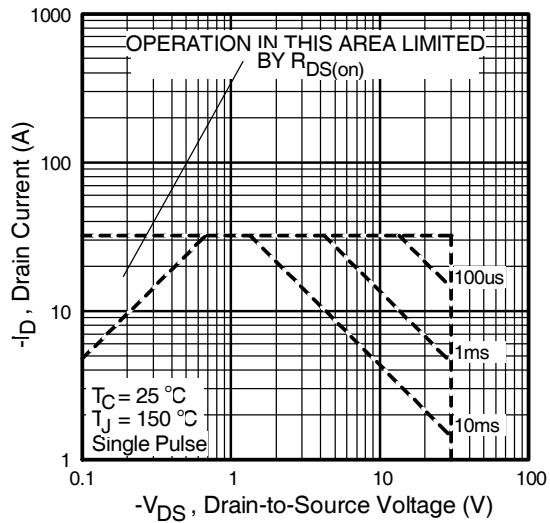
**Fig 5.** Typical Capacitance Vs.  
Drain-to-Source Voltage



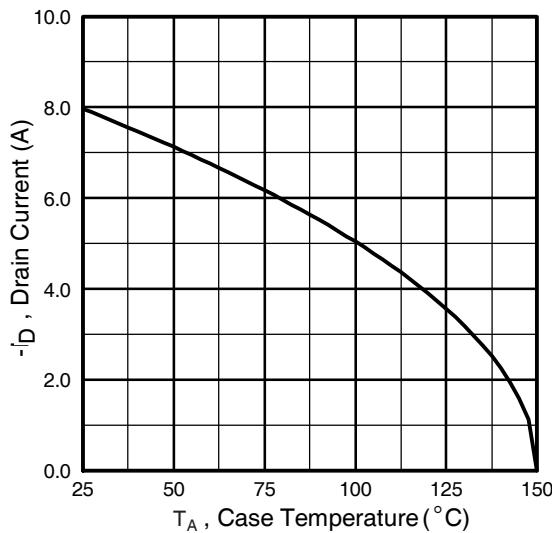
**Fig 6.** Typical Gate Charge Vs.  
Gate-to-Source Voltage



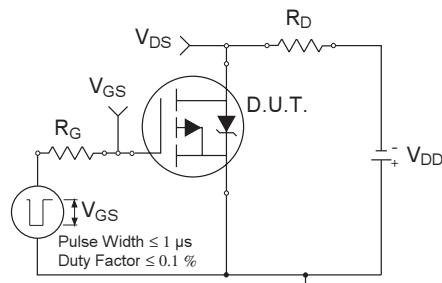
**Fig 7.** Typical Source-Drain Diode  
Forward Voltage



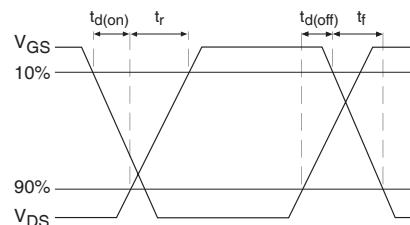
**Fig 8.** Maximum Safe Operating Area



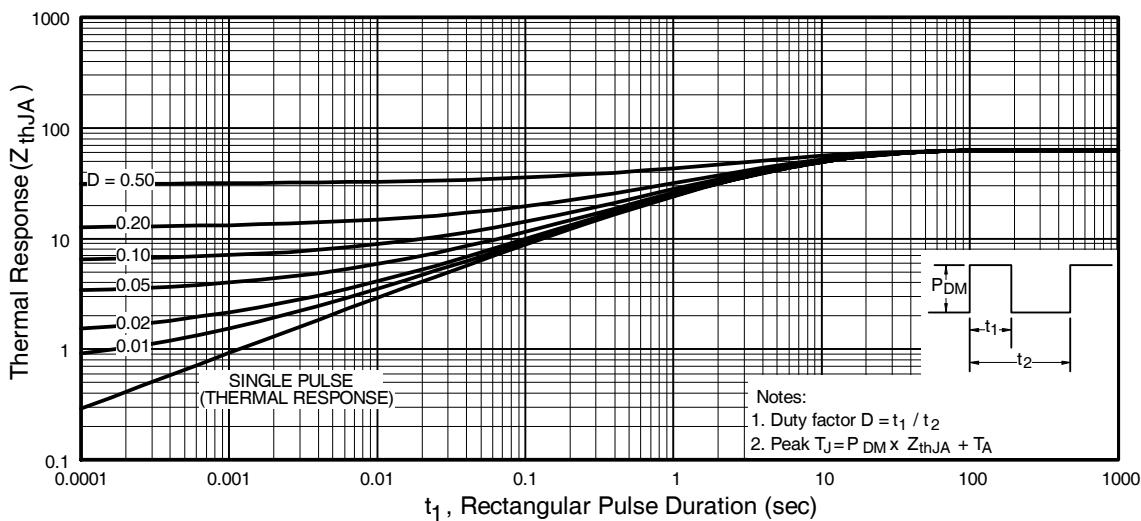
**Fig 9.** Maximum Drain Current Vs.  
Case Temperature



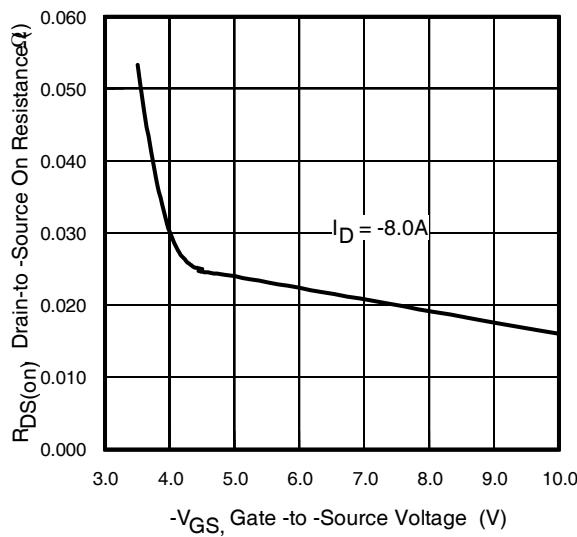
**Fig 10a.** Switching Time Test Circuit



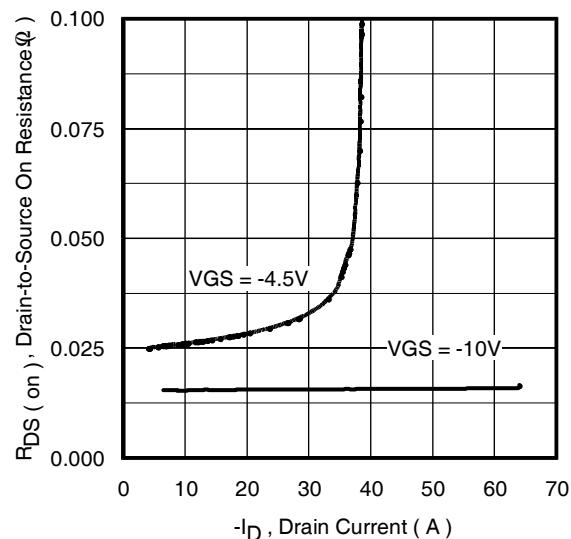
**Fig 10b.** Switching Time Waveforms



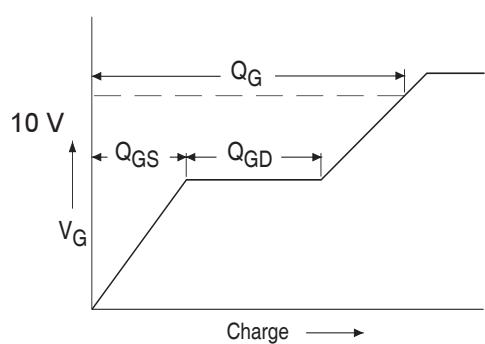
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



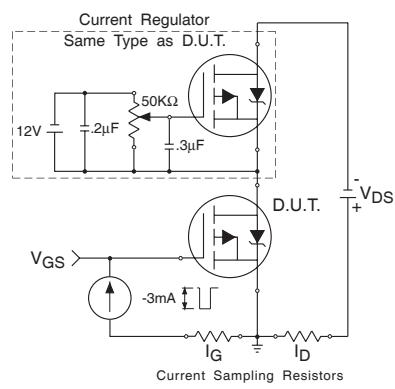
**Fig 12.** Typical On-Resistance Vs.  
Gate Voltage



**Fig 13.** Typical On-Resistance Vs.  
Drain Current

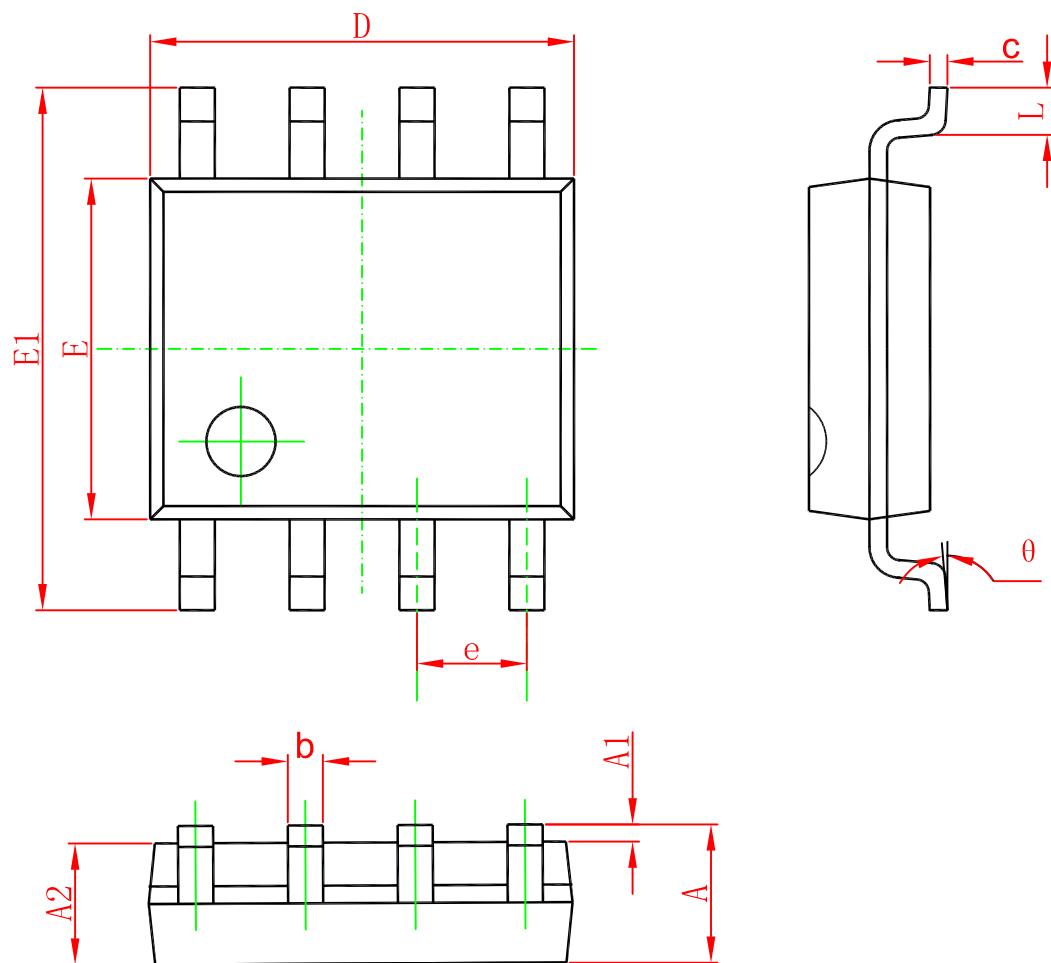


**Fig 14a.** Basic Gate Charge Waveform



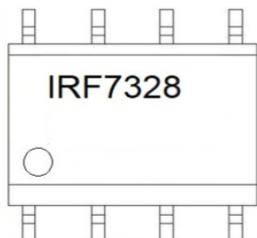
**Fig 14b.** Gate Charge Test Circuit

**SOP-8**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## **Marking**



## **Ordering information**

Order code	Package	Baseqty	Deliverymode
IRF7328TR	SOP-8	3000	Tape and reel